#### **Features**

- Fast Read Access Time 150 ns
- Fast Byte Write 200 μs or 1 ms
- Self-Timed Byte Write Cycle Internal Address and Data Latches Internal Control Timer

**Automatic Clear Before Write** 

- Direct Microprocessor Control DATA POLLING
- Low Power

30 mA Active Current

100 μA CMOS Standby Current

High Reliability

Endurance: 10<sup>4</sup> or 10<sup>5</sup> Cycles Data Retention: 10 Years

- 5V ± 10% Supply
- CMOS & TTL Compatible Inputs and Outputs
- JEDEC Approved Byte Wide Pinout
- Commercial and Industrial Temperature Ranges

#### **Description**

The AT28C16 is a low-power, high-performance Electrically Erasable and Program-mable Read Only Memory with easy to use features. The AT28C16 is a 16K memory organized as 2,048 words by 8 bits. The device is manufactured with Atmel's reliable nonvolatile CMOS technology.

The AT28C16 is accessed like a static RAM for the read or write cycles without the need of external components. During a byte write, the address and data are latched

(continued)

## **Pin Configurations**

Pin Name	Function		
A0 - A10 Addresses			
CE	Chip Enable		
ŌE	Output Enable		
WE	Write Enable		
I/O0 - I/O7	Data Inputs/Outputs		
NC	No Connect		
DC	Don't Connect		

PLCC
Top View

A7 NC VCC NC
NC DC WE

4 2 1 32 1 32 1 30
A6 5 28 A9
A4 7 27 NC
A2 9 25 OE
A1 10 24 A10
A0 11 23 CE
NC 12 22 VO7
VOO 1 1 2 DC 3 4 5
GND

\*= RDY/BUSY

Note: PLCC package pins 1 and 17 are DON'T CONNECT.

PDIP, SOIC Top View

	ſ		$\neg \neg$		1	
Α7	$\Box$	1		24		VCC
A6	П	2		23		A8
A5	₫	3		22		Α9
A4	$\Box$	4		21		WE
А3	$\Box$	5		20		ŌĒ
A2		6		19		A10
Α1	$\Box$	7		18	$\vdash$	CE
A0	□	8		17		I/O7
I/O0	$\Box$	9		16		I/O6
I/O1	□	10		15		I/O5
I/O2	d	11		14		I/O4
GND		12		13	Ь	I/O3

CMOS E<sup>2</sup>PROM

16K (2K x 8)

0540A





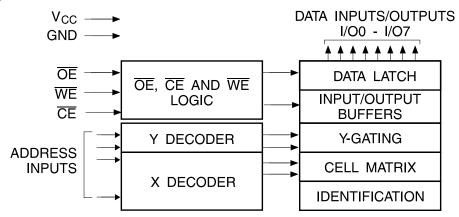
## **Description** (Continued)

internally, freeing the microprocessor address and data bus for other operations. Following the initiation of a write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. The end of a write cycle can be determined by DATA POLLING of I/O<sub>7</sub>. Once the end of a write cycle has been detected, a new access for a read or a write can begin.

The CMOS technology offers fast access times of 150 ns at low power dissipation. When the chip is deselected the standby current is less than 100  $\mu$ A.

Atmel's 28C16 has additional features to ensure high quality and manufacturability. The device utilizes error correction internally for extended endurance and for improved data retention characteristics. An extra 32-bytes of E<sup>2</sup>PROM are available for device identification or tracking.

#### **Block Diagram**



# **Absolute Maximum Ratings\***

Temperature Under Bias55°C to +125°C
Storage Temperature65°C to +150°C
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V
All Output Voltages with Respect to Ground0.6V to V <sub>CC</sub> + 0.6V
Voltage on $\overline{OE}$ and A9 with Respect to Ground0.6V to +13.5V

\*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **Device Operation**

**READ:** The AT28C16 is accessed like a Static RAM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in a high impedance state whenever CE or OE is high. This dual line control gives designers increased flexibility in preventing bus contention.

BYTE WRITE: Writing data into the AT28C16 is similar to writing into a Static RAM. A low pulse on the WE or CE input with  $\overline{OE}$  high and  $\overline{CE}$  or WE low (respectively) initiates a byte write. The address location is latched on the last falling edge of WE (or  $\overline{CE}$ ); the new data is latched on the first rising edge. Internally, the device performs a self-clear before write. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of  $t_{WC}$ , a read operation will effectively be a polling operation.

**FAST BYTE WRITE:** The AT28C16E offers a byte write time of 200 μs maximum. This feature allows the entire device to be rewritten in 0.4 seconds.

DATA POLLING: The AT28C16 provides DATA POLL-ING to signal the completion of a write cycle. During a write cycle, an attempted read of the data being written results in the complement of that data for I/O<sub>7</sub> (the other outputs are indeterminate). When the write cycle is finished, true data appears on all outputs.

**WRITE PROTECTION:** Inadvertent writes to the device are protected against in the following ways. (a)  $_{VCC}$  sense— if  $_{VCC}$  is below 3.8V (typical) the write function is inhibited. (b)  $_{VCC}$  power on delay— once  $_{VCC}$  has reached 3.8V the device will automatically time out 5 ms (typical) before allowing a byte write. (c) Write Inhibit—holding any one of  $_{OE}$  low,  $_{CE}$  high or  $_{WE}$  high inhibits byte write cycles.

CHIP CLEAR: The contents of the entire memory of the AT28C16 may be set to the high state by the CHIP CLEAR operation. By setting CE low and OE to 12 volts, the chip is cleared when a 10 msec low pulse is applied to WE.

**DEVICE IDENTIFICATION:** An extra 32-bytes of  $E^2PROM$  memory are available to the user for device identification. By raising A9 to  $12 \pm 0.5V$  and using address locations 7E0H to 7FFH the additional bytes may be written to or read from in the same manner as the regular memory array.





# **DC and AC Operating Range**

		AT28C16-15
Operating	Com.	0°C - 70°C
Temperature (Case)	Ind.	-40°C - 85°C
V <sub>CC</sub> Power Supply		5V ± 10%

# **Operating Modes**

Mode	CE	ŌĒ	WE	I/O	
Read	V <sub>I</sub> L	VIL	VIH	Dout	
Write (2)	VIL	VIH	VIL	DIN	
Standby/Write Inhibit	VIH	X <sup>(1)</sup>	Х	High Z	
Write Inhibit	X	Χ	VIH		
Write Inhibit	Χ	VIL	Х		
Output Disable	X	VIH	Χ	High Z	
Chip Erase	VIL	VH <sup>(3)</sup>	VIL	High Z	

Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .

2. Refer to AC Programming Waveforms.

3.  $V_H = 12.0V \pm 0.5V$ .

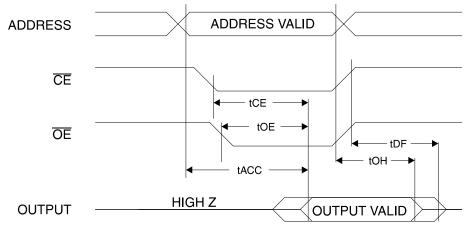
## **DC Characteristics**

Symbol	Parameter	Condition		Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V$ to $V_{CC} + 1V$			10	μΑ
ILO	Output Leakage Current	$V_{I/O} = 0V$ to $V_{CC}$			10	μΑ
I <sub>SB1</sub>	Vcc Standby Current CMOS	$\overline{\text{CE}}$ = V <sub>CC</sub> - 0.3V to V <sub>CC</sub> + 1.0V			100	μΑ
lone	V <sub>CC</sub> Standby Current TTL	$\overline{\text{CE}}$ = 2.0V to V <sub>CC</sub> + 1.0V	Com.		2	mA
I <sub>SB2</sub>	VCC Standby Current TTL	GE = 2.0V to VCC + 1.0V	Ind.		3	mA
loo	V <sub>CC</sub> Active Current AC	$\underline{f} = 5 \text{ MHz}; I_{OUT} = 0 \text{ mA}$	Com.		30	mA
Icc	VCC Active Current AC	CE = V <sub>IL</sub>	Ind.		45	mA
VIL	Input Low Voltage				8.0	V
VIH	Input High Voltage			2.0		V
VoL	Output Low Voltage	I <sub>OL</sub> = 2.1 mA			.4	V
Vон	Output High Voltage	I <sub>OH</sub> = -400 μA		2.4		V

### **AC Read Characteristics**

		AT28C16-15		
Symbol	Parameter	Min	Max	Units
tacc	Address to Output Delay		150	ns
t <sub>CE</sub> (1)	CE to Output Delay		150	ns
toe (2)	OE to Output Delay	10	70	ns
t <sub>DF</sub> (3, 4)	CE or OE High to Output Float	0	50	ns
toH	Output Hold from OE, CE or Address, whichever occurred first	0		ns

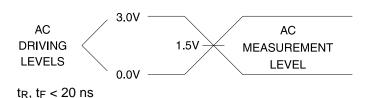
# AC Read Waveforms (1, 2, 3, 4)



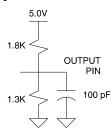
Notes: 1.  $\overline{\text{CE}}$  may be delayed up to  $t_{ACC}$  -  $t_{CE}$  after the address transition without impact on  $t_{ACC}$ .

- 2. OE may be delayed up to tce toe after the falling edge of CE without impact on tce or by tacc toe after an address change without impact on tacc.
- 3.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first  $(C_L = 5 \text{ pF})$ .
- 4. This parameter is characterized and is not 100% tested.

# **Input Test Waveforms and Measurement Level**



## **Output Test Load**



# Pin Capacitance (f = 1 MHz, T = $25^{\circ}$ C) (1)

	Тур	Max	Units	Conditions
Cin	4	6	pF	$V_{IN} = 0V$
Соит	8	12	pF	$V_{OUT} = 0V$

Note: 1. This parameter is characterized and is not 100% tested.



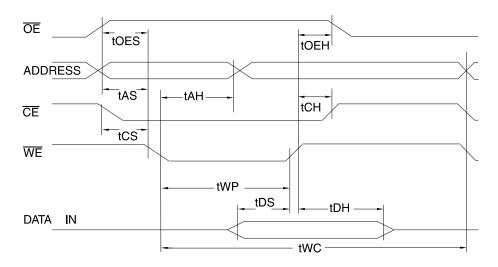


## **AC Write Characteristics**

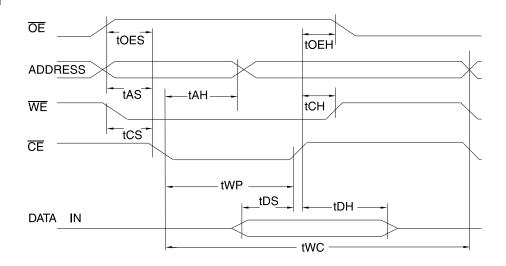
Symbol	Parameter		Min	Тур	Max	Units
tas, toes	Address, OE Set-up Time		10			ns
t <sub>AH</sub>	Address Hold Time		50			ns
twp	Write Pulse Width ( $\overline{\text{WE}}$ or $\overline{\text{CE}}$ )		100		1000	ns
t <sub>DS</sub>	Data Set-up Time		50			ns
tDH, tOEH	Data, OE Hold Time		10			ns
tcs, tch	CE to WE and WE to CE Set-up and Hold Time		0			ns
turo	Write Cycle Time	AT28C16		0.5	1.0	ms
twc	Write Cycle Time	AT28C16E		100	200	μs

## **AC Write Waveforms**

### **WE** Controlled



### **CE** Controlled



AT28C16

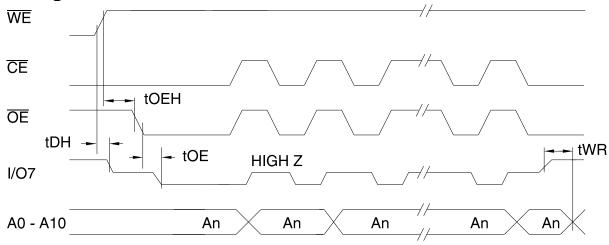
# **Data** Polling Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
tDH	Data Hold Time	10			ns
toeh	OE Hold Time	10			ns
toe	OE to Output Delay (2)				ns
t <sub>WR</sub>	Write Recovery Time	0			ns

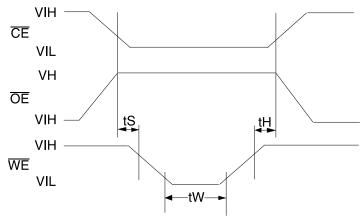
Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Characteristics.

# **Data** Polling Waveforms



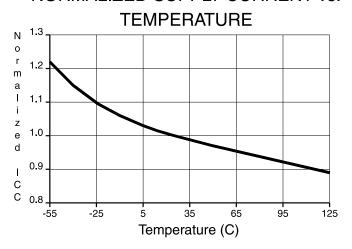
# **Chip Erase Waveforms**



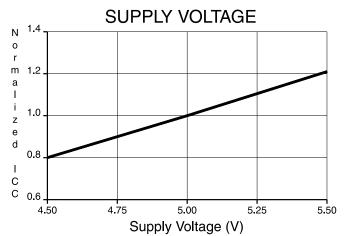
 $t_S = t_H = 1 \; \mu sec \; (min.)$   $t_W = 10 \; msec \; (min.)$   $V_H = 12.0V \pm 0.5V$ 



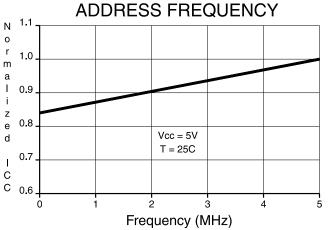
#### NORMALIZED SUPPLY CURRENT vs.



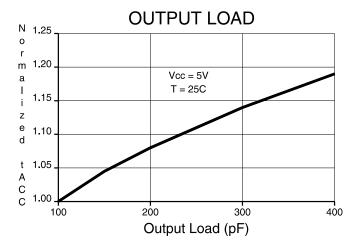
### NORMALIZED SUPPLY CURRENT vs.



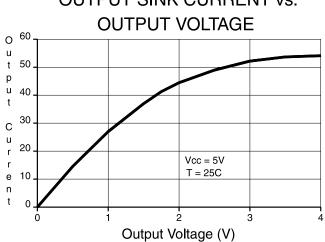
# NORMALIZED SUPPLY CURRENT vs.



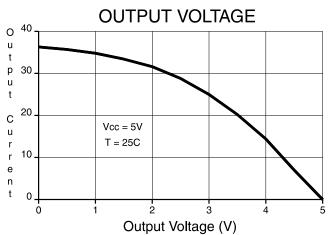
#### NORMALIZED ACCESS TIME vs.



**OUTPUT SINK CURRENT vs.** 



**OUTPUT SOURCE CURRENT vs.** 



# **Ordering Information** (1)

tACC	Icc	(mA)	Oudovina Codo	David and	Owner (for a Domina
(ns)	Active	Standby	Ordering Code	Package	Operation Range
150	30	0.1	AT28C16(E)-15JC AT28C16(E)-15PC AT28C16(E)-15SC	32J 24P6 24S	Commercial (0°C to 70°C)
	45	0.1	AT28C16(E)-15JI AT28C16(E)-15PI AT28C16(E)-15SI	32J 24P6 24S	Industrial (-40°C to 85°C)
250	30	0.1	AT28C16-W	DIE	Commercial (0°C to 70°C)

- Notes: 1. See Valid Part Number table below.
  - 2. The 28C16 200 ns and 250 ns speed selections have been removed from valid selections table and are replaced by the faster 150 ns TAA offering.
  - 3. The 28C16 ceramic package offerings have been removed. New designs should utilize the 28C256 ceramic offerings.

#### **Valid Part Numbers**

The following table lists standard Atmel products that can be ordered.

Device Numbers	Speed	Package and Temperature Combinations	
AT28C16	15	JC, JI, PC, PI, SC, SI	
AT28C16E	15	JC, JI, PC, PI, SC, SI	
AT28C16	-	W	

Package Type	
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)
24P6	24 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
24S	24 Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)
W	Die
Options	
Blank	Standard Device: Endurance = 10K Write Cycles; Write Time = 1 ms
E	High Endurance Option: Endurance = 100K Write Cycles; Write Time = 200 μs

